PATENT ASSIGNMENT

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NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Industrial Technology Research Institute	11/13/2006

RECEIVING PARTY DATA

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PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12405103

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Total Attachments: 2
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ASSIGNMENT

UTILITY

WHEREAS, I (we), Industrial Technology Research Institute, whose post office address(es) appears below, hereinafter referred to as ASSIGNOR, is (are) the owner(s) of certain new and useful improvements in the U.S. Patent Applications listed on the attached APPENDIX A: and

WHEREAS, TransPacific IP Ltd., whose post office address is Room 1402, 14th Fl., No. 205, Dunhua N. Road, Taipei City 105, Taiwan, R.O.C. hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire rights, titles and interests in and to the above-listed patent applications in the United States and throughout the world;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said INVENTIONS and applications throughout the United States of America, including any and all United States Letters Patents granted on any divisions, continuations, continuation-in-parts and reissues of said applications; and the entire rights, titles and interests in and to the said INVENTIONS throughout the world, including the rights to apply for patents and inventor certificates in respect thereof and to claim priority pursuant to rights accorded ASSIGNOR under the terms of the Paris International Convention and all other available international conventions and treaties; and the entire rights, titles and interests in and to any and all patents, patents of addition, utility models, patents of importation, revalidation patents and inventor certificates which may be granted throughout the world in respect of said INVENTIONS

ALSO, ASSIGNOR hereby agrees to executed any documents that legally may be required in connection with the filing, prosecution and maintenance of said applications or any other patent applications or inventor certificates in the United States and in foreign countries for said INVENTIONS, including additional documents that may be required to affirm the rights of ASSIGNEE is and to said INVENTIONS, all without further consideration ASSIGNOR also agrees, without further consideration and at ASSIGNEE's expense, to identify and communicate to ASSIGNEE at ASSIGNEE's request documents and information concerning the INVENTIONS that are within ASSIGNOR's possession or control, and to provide further assurances and testimony on behalf of ASSIGNEE that lawfully may be required of ASSIGNOR in respect of the prosecution, maintenance and defense of any patent application or patent encompassed within the terms of this instrument ASSIGNOR's obligations under this instrument shall extend to ASSIGNOR's heirs, executors, administrators and other legal representatives

ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all United States Letters Patents referred to above to ASSIGNEE, as the ASSIGNEE of the entire rights, titles and interests in and to the same, for ASSIGNEE's sole use and behoof; and for the use and behoof of ASSIGNEE's legal representatives and successors, to the full end of the term for which such Letters Patents may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment and sale not been made.

ASSIGNOR authorizes Berkeley Law & Technology Group to insert or complete any information in this document needed to effect its recordal in the U S Patent and Trademark Office.

Assignor Name. **Industrial Technology Research Institute**	*Address.* No. 195, Sec. 4, Chung Hsing Rd., Chutung, Hsinchu, Taiwan, 310, R.O.C.
Representative: **Benjamin Wang** *Title:* **Deputy General Director**	
Signature: Benjamin Wang	*Date:* Nov. 13, 2006
Assignee Name **TransPacific IP Ltd.**	*Address* Room 1402, 14th Fl., No 205, Dunhua N. Road, Taipei City 105, Taiwan, R O C.
Representative **Guy L. Prouix** *Title* **Chairman**	
Signature Guy L Prouix	*Date* 15 Nov 2006

APPENDIX A

Atty Dkt:

U.S. Patent Application No.	Filing Date	Title
11/180,714	2005/07/14	Substrate-triggered bipolar junction transistor and ESD protection circuit
10/446,049	2003/05/28	On-chip latch-up protection circuit
11/137,173	2005/05/25	Depletion switch for esd protection
11/004,348	2004/12/03	Diode and applications thereof
11/205,378	2005/08/17	Diode strings and electrostatic discharge protection circuits
10/309,225	2002/12/04	Substrate-triggered bipolar junction transistor and ESD protection circuit
10/268,756	2002/10/11	Electrostatic discharge protection device for mixed voltage interface
11/045,300	2005/01/31	Electrostatic discharge protection device and method of manufacturing the same
10/307,969	2002/12/03	Electrostatic discharge protection device and method using depletion switch
10/428,047	2003/05/02	Esd protection circuits for mixed-voltage i/o buffers
10/727,550	2003/12/05	Turn-on-Efficient Bipolar Structures with Deep N-Well for On-Chip ESD Protection
10/726,641	2003/12/04	ESD Protection Design on connector/interface against Charged-device Model ESD Events
10/871,348	2004/06/21	Input Stage for Mixed-Voltage-Tolerant Buffer without Leakage Issue
11/017,053	2004/12/21	Novel poly diode structure for photo diode